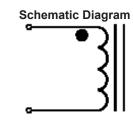
# Inductor



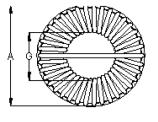


# RoHS Compliant

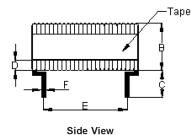
#### Note:

- 1. Wire UEFN/U (155°C) Ø0.8mm
- 2. 40TS (Reference) C.W

# **Configurations and Dimensions**



Front View



А	27mm (Max.)	
В	16.6mm (Max.)	
С	10 ±3mm	
D	0mm (Min.)	
E	21.8 ±2 mm	
F	Ø0.8mm (Ref.)	
G	8.8mm (Min.)	

# **Test Data for Mechanical**

Test Item	A mm	B mm	C mm	D mm	E mm	F mm	G mm
Specification	27 (Max.)	16.6 (Max.)	10 ±3	0 (Min.)	21.8 ±2	Ø0.8 (Ref.)	8.8 (Min.)
1	25.75	11.58	10.18	0.23	22.1	0.8	11.75
2	25.65	11.48	10.22	0.26	21.91	0.79	11.55
3	25.51	11.5	10.61	0.34	22.13	0.81	11.68
4	25.77	11.54	10.46	0.16	22.16	0.8	11.24
5	25.6	11.61	10.53	0.2	21.96	0.79	11.3
Average	25.66	11.54	10.4	0.24	22.05	0.8	11.5

#### **Material List**

No.	ltem	Material Description
1	Core	T90-75H-TAF200 (Green/Blue)
2	Wire	Ø0.8mm UEFN/U (155°C)
3	Solder (Lead-free)	Sn99.3% / Cu0.7%
4	Таре	9mm (W) × 2TS Yellow Mylar

# **Electrical Characteristics**

Test Condition		
10kHz / 0.25V	L	100µH ±20%
TA = 25°C	DCR	65mΩ (Max.)
10kHz / 0.25V Irms = 4.3A	ΔT	Temperature rise 40°C (Max.)

Operating temperature : -55°C to +130°C

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### **Reliability Test**

Test Item	Specifications		Test Mo	Test Method and Remarks		
Operating temperature range	-55°C to +130°C		Including temperature r	ise due to self-generated heat.		
Storage condition	Ambient temperature: 0°C to 40°CHumidity: Below 70% RH			the solderability of terminal electrodes, care en to control temperature and humidity in the a.		
Moisture sensitivity	DCR change :	No abnormality No damage Within ±5% Within ±5%	According to J-STD-02 Test condition Test duration Recovery	0B level 3 : 60°C 60% RH : 40 hrs : 1 to 2 hours of recovery under the standard condition after the removal from the test chamber.		
Solderability	All termination shall exhibit a continuous solder coating free from defects for a minimum of 95% of the surface area of any individual lead.		According to J-STD-00. Steam aging category Steam aging duration Solder Solder temperature Dip time	: 97°C 98% RH		

#### **Test Data for Electrical**

Test Item	L µH	DCR mΩ	ΔΤ
Condition	10kHz / 0.25V	TA = 25°C	10kHz / 0.25V Irms = 4.3A
Specification	100 ±20%	65 (Max.)	Temperature rise 40°C (Max.)
1	99.04	45.02	
2	97.7	45.15	
3	100.89	44.94	ОК
4	100.67	45.13	
5	101.71	45.41	
Average	100	45.13	ОК

# Part Number Table

Description	Part Number
Inductor, 100µH, 20%, 2 Pins	MCAP109020040K-101MU

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